

# StenTech™

Innovative Problem Solvers



The Leading SMT Printing Solutions Company

Incorporating  
**PHOTOSTENCIL** | **ATD** ADVANCED  
TOOLING  
DESIGN

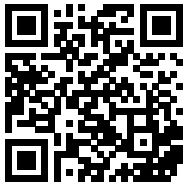
[www.stentech.com](http://www.stentech.com)



USA  
Mexico  
Canada

“Our mission is to empower customer success by being the trusted partner in delivering quality products and innovative solutions for leading electronic manufacturers.”

With 18 facilities and growing, we deliver with speed, precision, quality and care to our customers across the US Mexico and Canada.



SCAN FOR OUR LOCATIONS &

### Stencils

- Laser cut Stencils
- Electroform Stencils
- High Definition Print Stencils
- Advanced Nano Stencils
- Step Stencils
- Mini Steancils
- Emulsion Screen
- Online Ordering

### Tooling

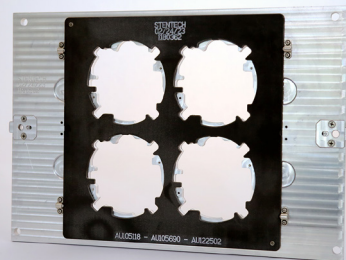
- Wave Solder Pallets
- SMT Carriers
- Pressfit Fixtures
- Conformal Coating Fixtures
- Hand Soldering Fixture
- Router Fixtures
- Vacuum Support
- Adjustable Pallets

## Easy Online Ordering

CUSTOMIZED CUSTOMER PORTAL



SCAN FOR WEBSITE



StenTech is the leading multinational SMT Printing Solutions company. We pride ourselves on being true partners to our customers, and being printing experts.

We have the capability and capacity to complete even the most demanding projects. By coupling highly trained professionals with the most advanced CNC equipment, laser technologies and the latest CAD/CAM software, StenTech Engineering offers industry leading quality and service.

Our facilities are equipped with the most advanced technology, and highly trained staff providing rapid turn-around service.

StenTech offers a wealth of knowledge and technical expertise that is unmatched. Our design team is seen as an extension of our customers' operation as true partners.

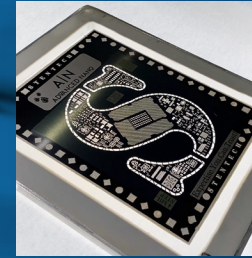
When you work with StenTech we create a tailor-made profile and footprint library and assist with designing and manufacturing your stencils and tooling to the highest caliber.

By working closely together we can catch problems before they become blogger issues down the line.

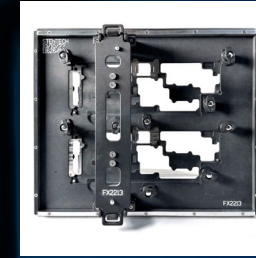
**We are a team of problem solvers.**

## PRODUCTS

### Stencils



### Solder Pallet & Tooling



### RF Shielding & Parts



With the continued miniaturization of electronic packaging and smaller PCB footprints, the challenge continues to be the ability to get enough solder paste down in the right geometry to not only place the component to solder but also to meet the ever challenging customer and IPC requirements.

Our CAD experts combine industry designs and modification rules, with your own specific design & production requirements and preferences to produce stencils that are right the first time.

This is only possible thanks to our proprietary StenCAD software, which allows us to accurately predict the transfer efficiency of paste/stencil aperture combinations and apply design rules to the stencil in order to optimize paste deposit repeatability - so essential when dealing with fine features and micro-scale devices.

StenTech has advanced capabilities in machining and drilling composite materials. We provide a wide range of manufacturing solutions for wave solder pallets that are custom engineered to each client's specification.

StenTech is able to produce precision thin metal shielding, lids and fencing for all types of RF electronic applications with extremely tight manufacturing tolerances that fit in complicated component spaces.

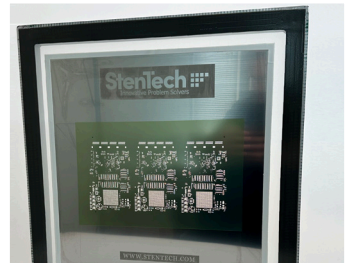
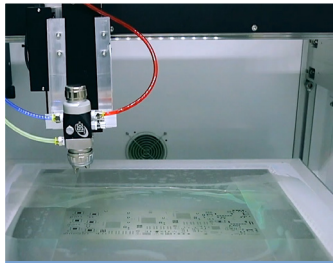
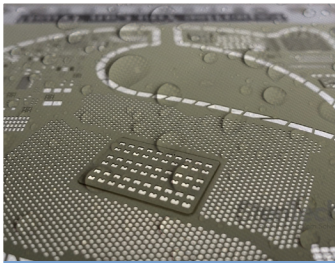
Additionally, a wide range of designs and applications offering tight tolerances for many different materials and thicknesses are available through our chemical-etching processes.

# Award winning StenTech Advanced Nano



Industry leading, premier stencil coating.

StenTech's "Advanced Nano" chemistry mitigates the pain points without losing any results in quality. We can now deliver a fully cured ready to use and ready to clean coated stencil the same day! Advanced Nano will change the way you build PCBA's, beyond the print.



## Lead time

- Lead time of a coated stencil AIN is ready for use 30 min after coating and can be delivered to you for and used same day.



## Durability

- AIN is more durable than any other coating on the market. You will not see the traditional premature wear or degradation of the coating - AIN is simply more robust.



## Precision

- Uniformed coating across the stencil, AIN thickness variance is +/- 1 micron across any stencil
- Paste release with enhanced hydrophobic and oleophobic properties.

## Key benefits

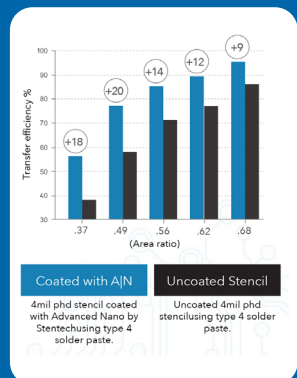
- Coating is cured and ready to use/clean in 30mins
- Abrasion resistant
- Chemical resistant acidic and alkaline from 4-11 ph
- Improved brick formation
- Increased transfer efficiency
- Excellent printing experience
- Industry Award winning



2023 CIRCUITS ASSEMBLY  
NPI Award

# 20%

Applying AIN to your solder stencil can increase paste release as much as 20%



# PHOTOSTENCIL

## A division of StenTech

Photo Stencil has been the premiere provider of advanced stencil printing solutions to the electronics assembly and semiconductor markets in the Americas since 1979. We design and manufacture high-performance stencils and tooling for a wide range of industries including: Semiconductor, SMT, Defense, Medical Devices and Automotive.

Our current market leading products include patented AMTX electroformed stencils (EForm), high-performance AccuScreen™ stencils, 3-D and step stencils as well as our cost-conserving NiCut stencil and we manufacture the highest print performance Electroform Nickel Stencils (AMTX) in the Americas.

### Electroform Nickel Stencils (AMTX)

- Improved under screen cleaner (USC) performance and reduced cleaning frequency
- Maximum life and performance when matched with Photo Stencils range of E-Blade squeegees
- Lower Area Ratios allows the use of thicker stencils for very small components
- No need for post-processing (Ni-plate or electro polish)



Smooth aperture walls promoting excellent paste transfer of E-form Ni Stencil

## StenTech LaserStep® STENCIL

A solution aimed at an everyday industry challenge. Diverse solder paste requirements for mixed technology PCB. Fine Pitch SMT components require a thin stencil in order to print a smaller solder paste quantity. While larger components require more solder paste for a better connection, consequently a thicker stencil. With the ability to extract pockets and weld different thicknesses back in, we can now leverage our LaserStep process to get the right paste for each component.

### A Solution for:

- Coplanarity
- Coating or height variations on PCB
- Two stage print stencil process

### Key Benefits:

- Various solder paste volumes in one print
- Step up or step down on both sides of the stencil.
- High tolerance positional accuracy.
- Quick turn time and next day delivery.

## RICOCEL®

A high heat resistant glass/epoxy laminate is our preferred material for Solder Pallets and Carriers with static dissipative property.

### Key Benefits

- High thermal conductivity
- The ability to cut .020" thick walls
- Capture all PTH locations
- Avoid using titanium inserts
- A more durable material to last double the cycles